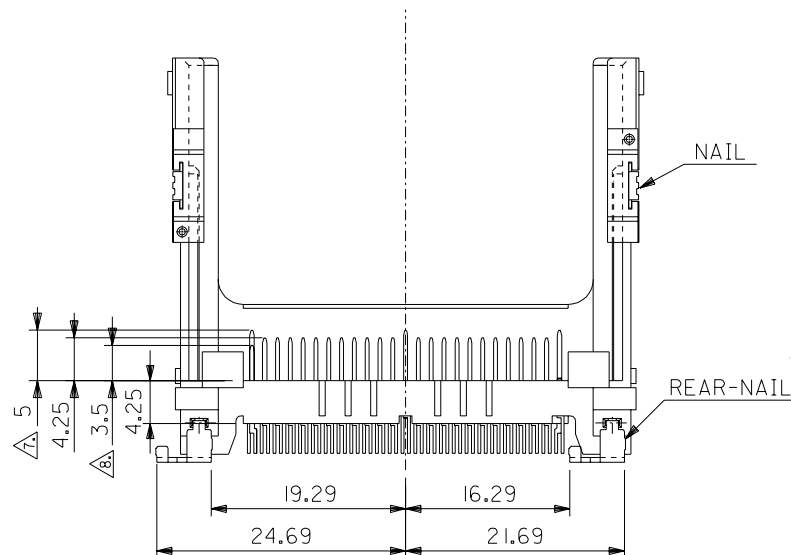
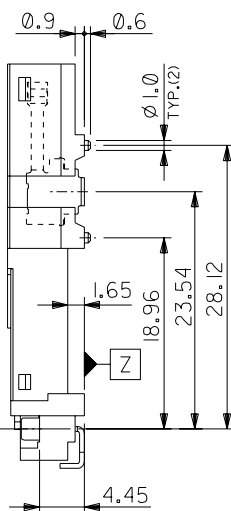
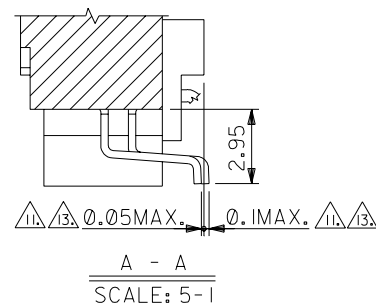




55358-5038		55358-5039		55358-50**	
HARD TRAY PACKAGE		MATERIAL No.		MODEL No.	
SCALE 2 - 1 ☒ mm ☐ INCH		THIRD ANGLE PROJECTION		DIMENSIONS: ☐ mm ☐ INCH ☐ mm ☐ mm ☒ mm ONLY	
DRAWN BY & DATE M.NABEI '04/04/22		TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL) -LEAD FREE-		SHT REV REVISE ON CAD ONLY	
CHECKED BY & DATE K.TOJO '04/04/22					
APPROVED BY & DATE H. Sano '04/04/22		MOLEX INCORPORATED			
CAD FILENAME SD-55358-015.S01		MATERIAL NO. SEE CHART		DRAWING NO. SD-55358-015 SHEET NO. 1 OF 2	
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.					SIZE B

DWG. NO. SD-55358-015

F

D

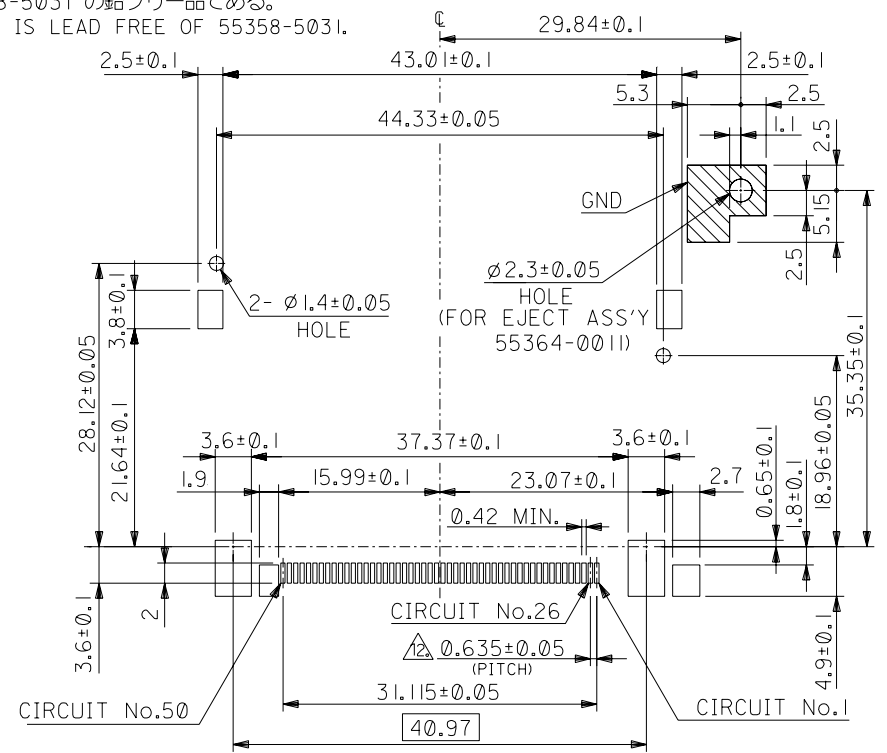
C

B

DO NOT SCALE DRAWING

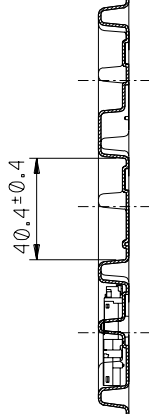
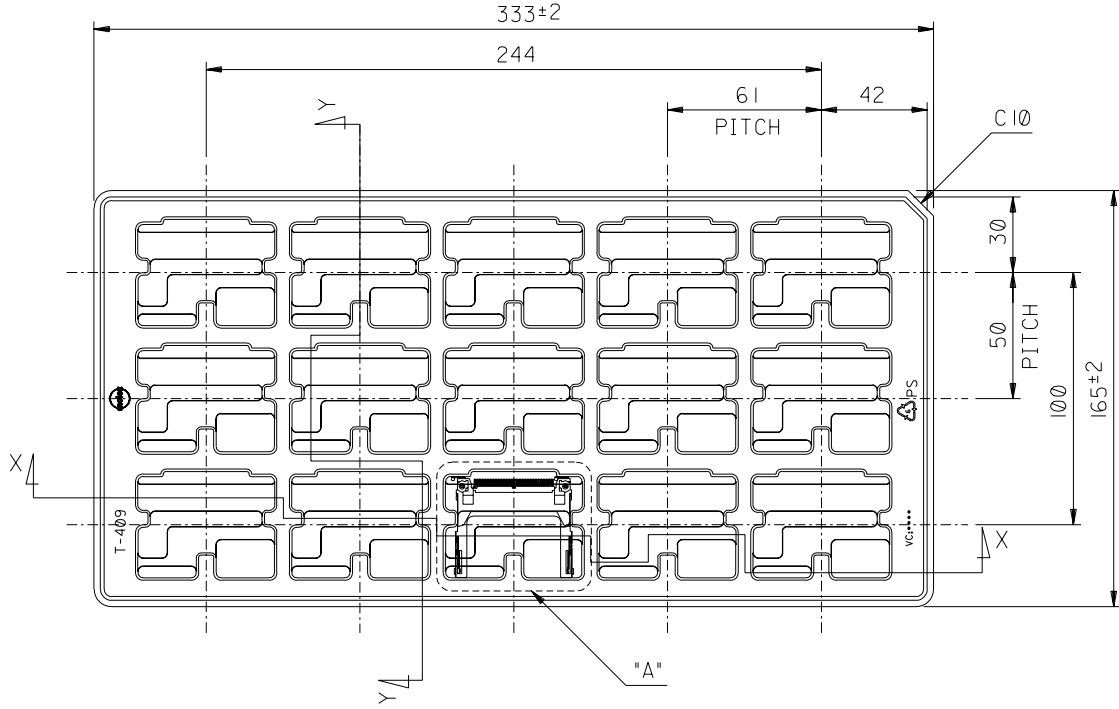
- 注) 1. 材質 MATERIAL
ハウジング: ガラス入りLCP UL94V-0
HOUSING: LIQUID CRYSTAL POLYMER G.F. UL94V-0
ピン: リン青銅
PIN: PHOSPHOR BRONZE
ネール: リン青銅 (t0.3)
NAIL: PHOSPHOR BRONZE (t0.3)
リヤネール: リン青銅 (t0.48)
REAR-NAIL: PHOSPHOR BRONZE (t0.48)
2. メッキ仕様 PLATING
ピン
接点部: 金メッキ
CONTACT AREA: GOLD
半田付け部: 錫メッキ
SOLDER TAIL AREA: TIN
下地メッキ: ニッケルメッキ
UNDERPLATING: NICKEL OVER ALL
ネール
接点部: 金メッキ
CONTACT AREA: GOLD
半田付け部: 錫メッキ
SOLDER TAIL AREA: TIN
下地メッキ: ニッケルメッキ
UNDERPLATING: NICKEL OVER ALL
リヤネール
錫メッキ
REAR-NAIL
TIN
下地メッキ: ニッケルメッキ
UNDERPLATING: NICKEL OVER ALL
3. 推奨基板厚: t=0.8 MIN.
RECOMMENDED P.C.B. THICKNESS: t=0.8 MIN.
4. 適合カード厚: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)
RECOMMENDED CARD THICKNESS: 3.3±0.1 (TYPE I) AND 5 MAX. (TYPE II)
5. 適合カード幅: 42.8±0.1
RECOMMENDED CARD WIDTH: 42.8±0.1
6. ハウジング色: 黒
HOUSING COLOR: BLACK
7. 寸法適用極: 1,13,38,50
THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 1,13,38 AND 50.
8. 寸法適用極: 25,26
THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.
9. ピンの倒れは、ピン根元を基準に全方向へ0.1 MAX.とする。
PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1 WHEN MEASURED FROM PIN BASE.
10. ピン根元に適用する。
THIS DIMENSION TO BE MEASURED AT PIN BASE.

11. ソルダータールは、Z面を基準とし上へ0.05下へ0.1の範囲にあり、且つソルダータールの平坦度は、0.1 MAX.とし、テール先端にて測定する。
SOLDERTAILS TO BE WITHIN 0.05 UPWARD AND 0.1 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF SOLDERTAILS TO BE WITHIN 0.1. MEASUREMENT POINT IS SOLDERTAILS TIP.
12. 公差非累積
NON-CUMULATIVE
13. テールとネール、リヤネールを併せた平坦度は、0.1 MAX.とする。
TOTAL COPLANARITY OF SOLDER TAILS, NAILS AND REAR-NAILS TO BE 0.1 MAX.
14. 本製品は 55358-5031 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55358-5031.

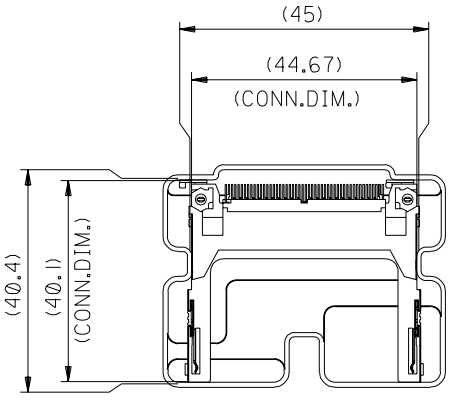


基板推奨寸法
RECOMMENDED P.C.B. LAYOUT

EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		EC NO. DRWN: CHK: APPR:		DESCRIPTION SEE SHEET 1 OF 2	MATERIAL 材料		GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		55358-50**		MODEL NO.		DIMENSIONS:		SHT	REV							
													SEE NOTES		SCALE 2 - 1		DESIGN UNITS ☒ mm ☐ INCH		 THIRD ANGLE PROJECTION		☐ mm INCH ☐ mm INCH ☒ mm ONLY		REVISE ON CAD ONLY								
													FINISH 仕上げ		10 UNDER 未満		±0.2		DRAWN BY & DATE M.NABEI '04/04/22		TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, NORMAL) -LEAD FREE-										
													SEE NOTES		10 OVER 以上 30 UNDER 未満		±0.25		CHECKED BY & DATE K.TOJO '04/04/22												
												WIRE RANGE 適用電線範囲		— # —		30 OVER 以上		±0.3		APPROVED BY & DATE M. Sasaki '04/04/22		MOLEX INCORPORATED									
												INS. RANGE 被覆外径		— # —		ANGLE 角度		±3°		CAD FILENAME SD-55358-015.S02		MATERIAL NO. — # —		DRAWING NO. SD-55358-015		SHEET NO. 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.		SIZE B	



SECT. Y-Y



DETAIL A
(SCALE 1-1)

NOTES

1. 一般公差: ±0.5
GENERAL TOLERANCES: ±0.5
2. 反り: 2MAX.
WARP: 2MAX.
3. 梱包数: 15個
PACKAGING QUANTITY: 15PCS.
4. 本製品は 55358-5026/-5036 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 55358-5026/-5036.

SECT. X-X

15		55358-5039		55358-5038		50	
		55358-5029		55358-5028			
梱包数量 QUANTITY		コネクタ番号 CONNECTOR No.		製品番号 MATERIAL No.		極数 CKT.	
MODEL NO.		DIMENSIONS:			SHT	REV	
20° 3RD ANGLE PROJECTION		☐ mm ☐ INCH ☒ mm ONLY			REVISE ON CAD ONLY		
TITLE:		TRAY FOR CF CARD CONN. 50P HEADER HS'G ASS'Y -LEAD FREE-					
MOLEX		MOLEX INCORPORATED					
MATERIAL NO. SEE CHART		DRAWING NO. SD-55358-016			SHEET NO. 1 OF 1		
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.						SIZE B	

DESIGN NO. J2004-3952		MATERIAL 材料		GENERAL TOLERANCES: (UNLESS SPECIFIED)	
DRWN: M.NABEI		POLYSTYRENE (t=1.0)		10 UNDER 未満 ±0.2	
CHK: K.TOJO		FINISH 仕上げ //		10 OVER 30 UNDER 未満 ±0.25	
APPR: M.SASAO		WIRE RANGE 適用電線範囲 //		30 OVER 以上 ±0.3	
REV		INS. RANGE 被覆外径 //		ANGLE 角度 ±3°	